ASSOCIATION CONNECTING ELECTRONICS INDUSTRIES® international	Composition D 2005. IPC, Bannocl and Pan-American	e claration (burn, Illinois. A copyright conver	all rights reserved untions.	inder both											sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				e *	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information									
upplier Information															
Company name* Company			ny unique ID			Unique ID Authority					Respons	Response Date*			
isemi										2023-06	2023-06-08				
ontact Name		Title - Conta	Title - Contact			Phone - Contact*				Email -	Email - Contact*				
Product-Env-Stewards		Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Repre	Title - Representative			Phone - Representative*				Email -	Email - Representative*					
roduct-Env-Stewards	Product Envi	Product Enviro Compliance			NA				Produc	Product-Env-Stewards@onsemi.com					
Requester Item Number	Requester Item Number Mfr Ite			Number Mfr Item Name			ctive Date Version Manufacturing Site		e ·	Weigh	t*	UOM	Unit Type		
	MT9J0 DP	MT9J003I12STMV- 10 MP 1/2 CIS		SO		2023-06-08		TWU		:	240.0		mg	Each	
Ianufacturing Proccess Inf	ormation						I								
Terminal Plating / Grid A	Terminal Plating / Grid Array Material Terminal		Alloy	J-STD-020 MS	SL Rating	Peak Process B		Body Temperature Max Time at Peal		Peak Temperat	Temperature Number of Reflow Cycles		cles		
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)		CU Alloy	U Alloy 4			260	С		30		secon	ds .	3		
omments															
For more information regarding m															

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU												
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all							
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	stislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	52.87	mg		Misc.	proprietary data	-	0.2009	mg
			Supplier	Silicon (Si)	7440-21-3		52.1457	mg
			Supplier	Aluminum (Al)	7429-90-5		0.5234	mg
Die Attach	2.57	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.9638	mg
			Supplier	Ethylene Glycol	107-21-1		0.0257	mg
			Supplier	Sulfonium (Thiodi-4,1-phenylene)	89452-37-9		0.0771	mg
			Supplier	Modified Silicon Dioxide (SiO2)	67762-90-7		0.5397	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.9637	mg
Imaging Lens	57.43	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.8715	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.8715	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.8715	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.8715	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2871	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.8715	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.8715	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		39.9138	mg
Lid Attach	2.4	mg	Supplier	2-phenoxy ethyl acrylate	48145-04-6		1.08	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.48	mg
			Supplier	Filler (SiO2)	68909-20-6		0.3	mg
			Supplier	Acrylate Oligomer	Proprietary Data		0.012	mg
			Supplier	Curative	Proprietary Data		0.048	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.48	mg
Mold Compound-Black	45.77	mg		Phenolic Resin	proprietary data		6.8655	mg
			Supplier	Oxirane	39817-09-9		6.8655	mg
			Supplier	1,4-Bis(2,3-epoxypropoxy)butane	2425-79-8		1.3731	mg
			Supplier	Carbon Black (C)	1333-86-4		0.4577	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		29.2928	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.9154	mg
Substrate and Solder Mask	78.72	mg	Supplier	Fiber Glass (SiO2)	65997-17-3		16.6808	mg
			Supplier	Inorganic Filler of Solder Mask_Talc (Mg3Si4O10(OH)2)	14807-96-6		1.0312	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.2598	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

			Supplier	Acetophenone Derivative	Proprietary Data	1.5429	mg
			Supplier	Carbon Black (C)	1333-86-4	0.2519	mg
			Supplier	2,4-Diethyl-9H-thioxanthen-9-one (DETX)	82799-44-8	0.2598	mg
			Supplier	Solvent Naphtha (Solvent oil)	64742-94-5	3.0858	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data	10.2966	mg
			Supplier	Copper (Cu)	7440-50-8	37.329	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	7.9822	mg
Wire Bond - Au	0.24	mg	Supplier	Gold (Au)	7440-57-5	0.24	mg